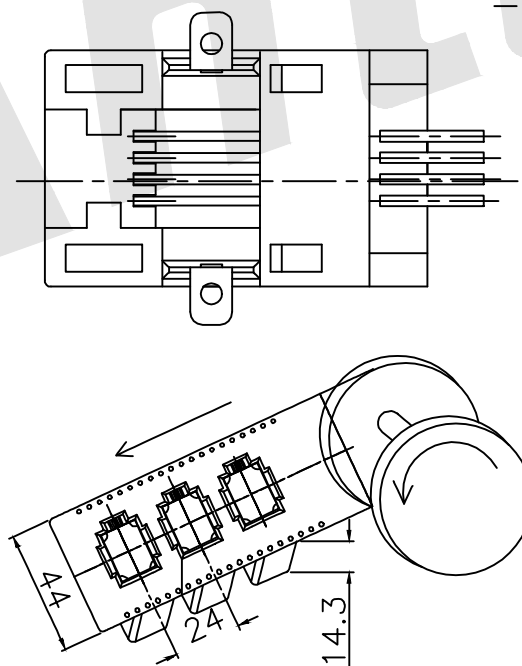
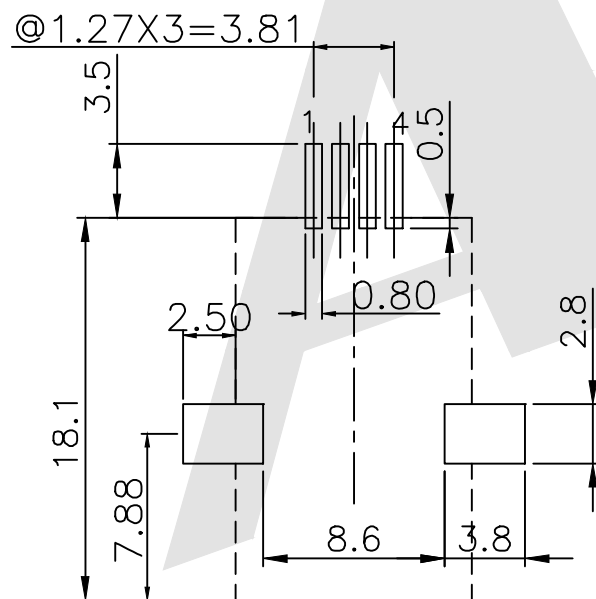
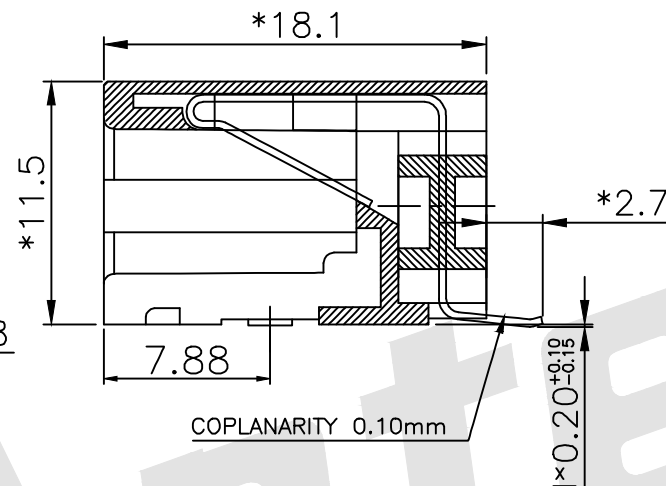
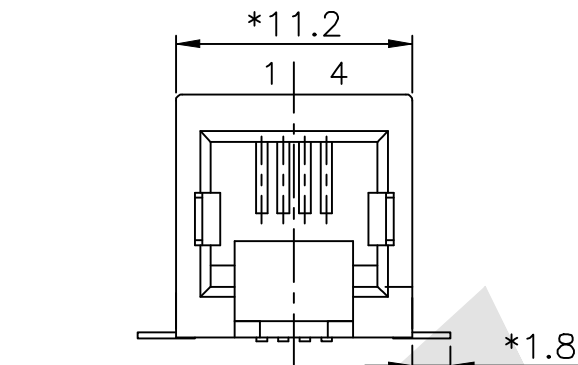


HSF



ROHS



MATERIAL:

1. HOUSING MATERIAL: GLASS FILLED POLYESTER UL94V-0.
2. CONTACT MATERIAL: PHOSPHOR BRONZE $t=0.35\text{mm}$
3. PLATING: SELECTING GOLD PLATING
1u"~50u" OVER NICKEL IN CONTACT AREA. 150u" TIN PLATING OVER NICKEL IN SOLDER AREA.
4. SHIELD: 0.25mm THICKNESS COPPER ALLY WITH NICKEL . PLATEL

ELECTRICAL:

1. VOLTAGE PATING : 125 VAC RMS.
2. CURRENT PATING : 1.5 AMP
3. CONTACT RESISTANCE : 35 MILLIOHMS MAX
4. INSULATION RESISTANCE: 1000 MEGOHMS MIN @ 500V DC.
5. DIELECTRIC WITHSTANDING RESISTANCE: 1000V AC RMS 60Hz. 1MIN

MECHANICAL:

1. DURRABILITY: 750 CYCLES MIN
2. PCB RETENTION PRE-SOLDER : 10LB MIN

ENVIRONMENTAL:

1. STORAGE: -40°C TO +85°C .
2. OPERATION: -40°C TO +85°C .
3. IR REFLOW SOLDERING

TEMPERRATURE: 255~265°C (5~10 SECONDS) MATES WITH MODULAR PLUG CONFORMING TO FCC PART 68 SUBPART F.

Order Code:

ATRJ5827 - 4P - 4C - X - A - A

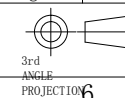
①	②	③	④	⑤	⑥
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- ① SERIES NO:
② NUMBER OF POSITIONS (8P, 6P, 4P)
③ NUMBER OF CONTACTS (8C, 6C, 4C)
④ Contact Plating
G0: Gold flash
G1: 3U" Gold
G2: 5U" Gold
G3: 10U" Gold
G4: 15U" Gold
G5: 30U" Gold
SN: Tin

- ⑤ Shield
A: W/O Shield
B: Half Shield
C: Shield W/Eml
D: Shield W/O Eml
⑥ packing:
A: Tray packing
R: Tape & Reel

Unless Otherwise specified tolerance
X. ± 0.35 X. XX: ± 0.20
X. X: ± 0.25 X. XXX: ± 0.15

SCALE: As Shown	UNIT: mm
DRAW Wu Feng Rong	DATE 22/03/2018
CHECK BobYang	DATE 22/03/2018



ANTENK ELECTRONICS CO., LTD
Http://www.antenk.com
E-mail: sales@antenk.com

TITLE:

RJ45 SIDE ENTRY SMT JACK 4P

DRAWING NO: ATRJ5827-4P4C-X-A-X

PRODUCT NO: ATRJ5827-4P4C-X-A-X

REV

DESCRIPTION

DATE

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4

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